

Product Change Notification - KSRA-06EAOV171

Date: 02 Mar 2018
Product Category: USB Bridge; Capacitive Touch Sensors; 8-bit PIC Microcontrollers; USB Power Delivery
Notification subject: CCB 3055 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 16L QFN package at NSEB assembly site
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 16L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach, G770HCD or G700LTD molding compound and EFTEC-64T or C194 lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach I, G700LTD molding compound and C194 lead frame material

Pre and Post Change Summary:

	Pre Change			Post Change
Assembly Site	UTAC Thai Limited LTD. / NSEB			UTAC Thai Limited LTD. / NSEB
Wire material	Au Wire			CuPdAu Wire
Die attach material	8200T	8600	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD	G700LTD
Lead frame material	C194	C194	EFTEC-64T	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

April 02, 2018 (date code: 1814)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	August 2017					-->	March 2018					April 2018				
	31	32	33	34	35		09	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date		X														
Qual Report Availability							X									
Final PCN Issue Date							X									
Estimated Implementation Date												X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

August 10, 2017: Issued initial notification.

March 02, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on April 02, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-06EAOV171_Qual_Report.pdf](#)
- [PCN_KSRA-06EAOV171_Affected_CPN.pdf](#)
- [PCN_KSRA-06EAOV171_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-06EAOV171
CATALOG_PART_NBR
MCP2221A-I/ML
MCP2221AT-I/ML
MCP2221-I/ML
MCP2221T-I/ML
MTCH105-I/ML
MTCH105T-I/ML
PIC16F1454-E/ML
PIC16F1454-I/ML
PIC16F1454T-I/ML
PIC16F1455-E/ML
PIC16F1455-I/ML
PIC16F1455-I/MLC02
PIC16F1455T-I/ML
PIC16F1455T-I/MLC02
PIC16F1503-E/MG
PIC16F1503-I/MG
PIC16F1503-I/MG031
PIC16F1503-I/MGC02
PIC16F1503T-E/MG
PIC16F1503T-E/MG033
PIC16F1503T-E/MG039
PIC16F1503T-I/MG
PIC16F1503T-I/MG027
PIC16F1503T-I/MG028
PIC16F1503T-I/MG029
PIC16F1503T-I/MG030
PIC16F1503T-I/MG031
PIC16F1503T-I/MG032
PIC16F1503T-I/MG035
PIC16F1503T-I/MG037
PIC16F1503T-I/MG043
PIC16F1503T-I/MG044
PIC16F1503T-I/MG048
PIC16F1503T-I/MGC02
PIC16F1613-E/ML
PIC16F1613-I/ML
PIC16F1613T-I/ML
PIC16F1613T-I/ML023
PIC16F1614-E/ML
PIC16F1614-I/ML
PIC16F1614T-I/ML
PIC16F1615-E/ML
PIC16F1615-I/ML

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CATALOG_PART_NBR
PIC16F1615T-I/ML
PIC16F1703-E/ML
PIC16F1703-I/ML
PIC16F1703T-I/ML
PIC16F1704-E/ML
PIC16F1704-I/ML
PIC16F1704T-E/ML
PIC16F1704T-I/ML
PIC16F1705-E/ML
PIC16F1705-I/ML
PIC16F1705T-E/ML
PIC16F1705T-I/ML
PIC16F1764-E/ML
PIC16F1764-I/ML
PIC16F1764T-E/ML
PIC16F1764T-I/ML
PIC16F1765-E/ML
PIC16F1765-I/ML
PIC16F1765T-I/ML
PIC16F1823-E/ML
PIC16F1823-I/ML
PIC16F1823-I/ML029
PIC16F1823-I/MLLS1
PIC16F1823T-E/ML
PIC16F1823T-I/ML
PIC16F1823T-I/ML029
PIC16F1823T-I/MLLS1
PIC16F1824-E/ML
PIC16F1824-I/ML
PIC16F1824T-E/ML
PIC16F1824T-I/ML
PIC16F1824T-I/MLC01
PIC16F1824T-I/MLOPP
PIC16F1825-E/ML
PIC16F1825-H/ML
PIC16F1825-I/ML
PIC16F1825T-E/ML
PIC16F1825T-E/ML031
PIC16F1825T-H/ML
PIC16F1825T-I/ML
PIC16LF1454-E/ML
PIC16LF1454-I/ML
PIC16LF1454T-I/ML

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CATALOG_PART_NBR
PIC16LF1455-E/ML
PIC16LF1455-I/ML
PIC16LF1455T-I/ML
PIC16LF1503-E/MG
PIC16LF1503-I/MG
PIC16LF1503-I/MG022
PIC16LF1503-I/MGC02
PIC16LF1503T-E/MG
PIC16LF1503T-I/MG
PIC16LF1503T-I/MG022
PIC16LF1503T-I/MGC02
PIC16LF1554-E/ML
PIC16LF1554-I/ML
PIC16LF1554T-I/ML
PIC16LF1613-E/ML
PIC16LF1613-I/ML
PIC16LF1613T-I/ML
PIC16LF1614-E/ML
PIC16LF1614-I/ML
PIC16LF1614T-I/ML
PIC16LF1615-E/ML
PIC16LF1615-I/ML
PIC16LF1615T-I/ML
PIC16LF1703-E/ML
PIC16LF1703-I/ML
PIC16LF1703T-I/ML
PIC16LF1704-E/ML
PIC16LF1704-I/ML
PIC16LF1704T-I/ML
PIC16LF1705-E/ML
PIC16LF1705-I/ML
PIC16LF1705T-I/ML
PIC16LF1764-E/ML
PIC16LF1764-I/ML
PIC16LF1764T-I/ML
PIC16LF1765-E/ML
PIC16LF1765-I/ML
PIC16LF1765T-I/ML
PIC16LF1823-E/ML
PIC16LF1823-I/ML
PIC16LF1823-I/MLC04
PIC16LF1823-I/MLLS2
PIC16LF1823T-I/ML

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CATALOG_PART_NBR
PIC16LF1823T-I/MLC04
PIC16LF1823T-I/MLLS2
PIC16LF1824-E/ML
PIC16LF1824-I/ML
PIC16LF1824-I/MLC01
PIC16LF1824T-I/ML
PIC16LF1824T-I/MLC01
PIC16LF1825-E/ML
PIC16LF1825-I/ML
PIC16LF1825T-E/ML
PIC16LF1825T-I/ML
UTC2000/MG
UTC2000-E/MG
UTC2000-I/MG
UTC2000T/MG
UTC2000T-E/MG
UTC2000T-I/MG